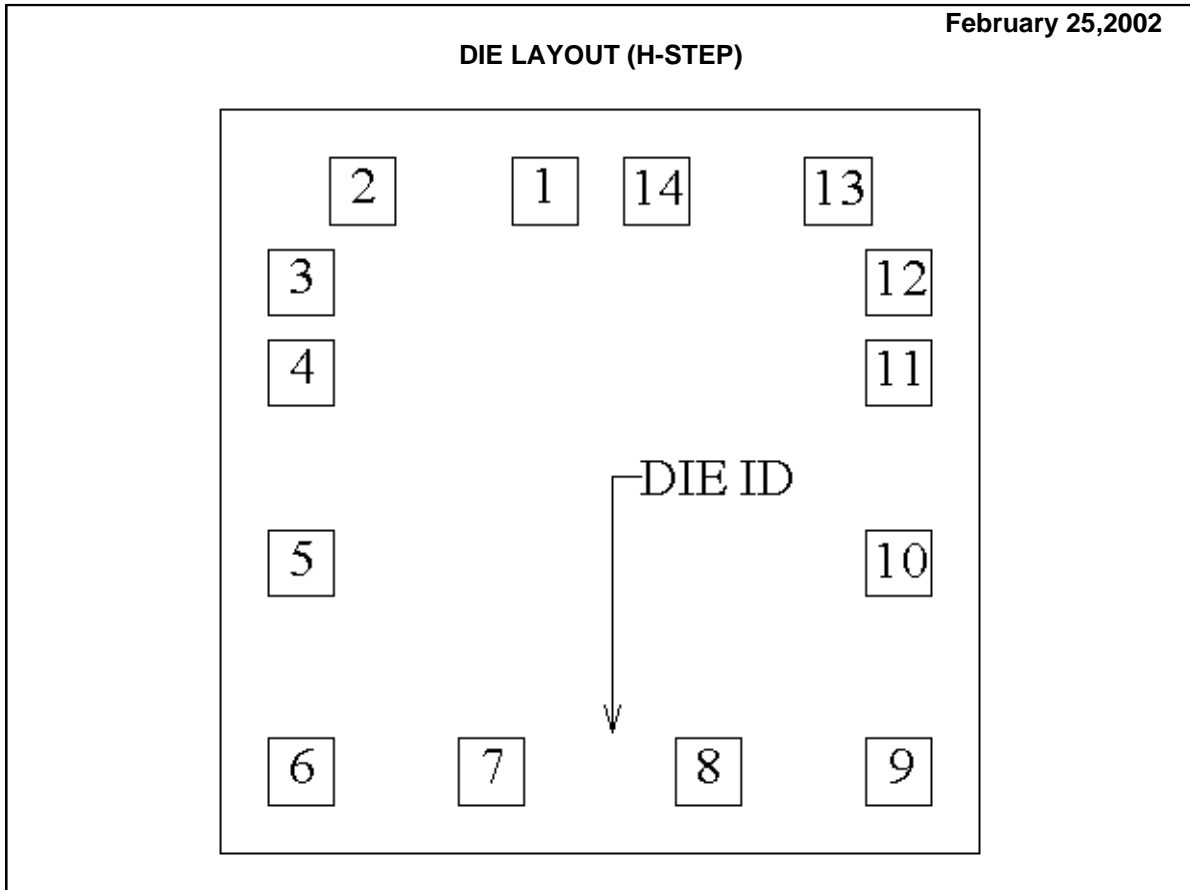


**LM2901 MDA MWA
LOW POWER LOW OFFSET VOLTAGE QUAD COMPARATORS**



DIE/WAFER CHARACTERISTICS

| Fabrication Attributes | | General Die Information | |
|-----------------------------|------------------------------------|-----------------------------|-----------------|
| Physical Die Identification | 1901H | Bond Pad Opening Size (min) | 92µm x 92µm |
| Die Step | H | Bond Pad Metalization | ALUMINUM |
| Physical Attributes | | Passivation | VOM NITRIDE |
| Wafer Diameter | 150mm | Back Side Metal | Bare Back |
| Die Size (Drawn) | 1067µm x 1041µm 42mils x 41mils | Back Side Connection | Floating or GND |
| Thickness | 330µm Nominal | | |
| Min Pitch | 127µm Nominal | | |

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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| Die Bond Pad Coordinate Locations (H -Step) | | | | | | |
|--|----------------|-----------------|------|----------|---|----|
| (Referenced to die center, coordinates in μm) NC = No Connection | | | | | | |
| SIGNAL NAME | PAD# NUMBER | X/Y CORRDINATES | | PAD SIZE | | |
| | | X | Y | X | Y | |
| Output 2 | 1 | -77 | 407 | 92 | x | 92 |
| Output 1 | 2 | -333 | 407 | 92 | x | 92 |
| V+ | 3 | -420 | 280 | 92 | x | 92 |
| -Input 1 | 4 | -420 | 153 | 92 | x | 92 |
| +Input 1 | 5 | -420 | -115 | 92 | x | 92 |
| -Input 2 | 6 | -420 | -407 | 92 | x | 92 |
| +Input 2 | 7 | -152 | -407 | 92 | x | 92 |
| -Input 3 | 8 | 152 | -407 | 92 | x | 92 |
| +Input 3 | 9 | 420 | -407 | 92 | x | 92 |
| -Input 4 | 10 | 420 | -115 | 92 | x | 92 |
| +Input 4 | 11 | 420 | 153 | 92 | x | 92 |
| GND | 12 | 420 | 280 | 92 | x | 92 |
| Output 4 | 13 | 334 | 407 | 92 | x | 92 |
| Output 3 | 14 | 79 | 407 | 92 | x | 92 |

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IN U.S.A.

Tel: 1 877 Dial Die (1 877 342 5343)
Fax: 1 207 541 6140

IN EUROPE

Tel: 49 (0) 8141 351492 / 1495
Fax: 49 (0) 8141 351470

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Tel: (852) 27371701

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